Product Preview **ESBC Rated NPN Silicon** Transistor

Features

- Low Equivalent On Resistance
- Very Fast Switch: 150 kHz
- Squared RBSOA: Up to 1500 V
- Avalanche Rated
- Low Driving Capacitance, No Miller Capacitance (Typ. 12 pF Capacitance at 200 V)
- Low Switching Losses
- Reliable HV Switch: No False Triggering due to High dv/dt Transients

Applications

- High–Voltage and High–Speed Power Switches
- Emitter–Switched Bipolar/MOSFET Cascode (ESBC)
- Smart Meters, Smart Breakers, HV Industrial Power Supplies
- Motor Drivers and Ignition Drivers

MAXIMUM RATINGS (T_{.1} = 25°C unless otherwise stated)

		-	
Parameter	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	1500	V
Collector–Emitter Voltage	V _{CEO}	800	V
Emitter-Base Voltage	V _{EBO}	12	V
Collector Current	۱ _C	2	А
Collector Current (Pulse)	I _{CP}	3	А
Base Current	Ι _Β	1	А
Base Current (Pulse)	I _{BP}	2	А
Power Dissipation ($T_C = 25^{\circ}C$)	PD	110	W
Operating and Junction Temperature Range	TJ	–55 to +125	°C
Storage Temperature Range	T _{STG}	–65 to +150	°C
Avalanche Energy (T _J = $25^{\circ}C$, 8 mH)	EAS	3.5	mJ

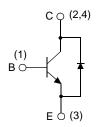
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Figure of Merit.



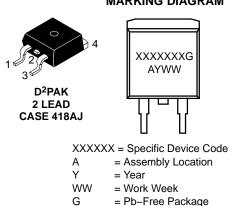
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V _{CS(ON)}	Equiv. R _{DS(ON)}	I _C
0.131 V	0.261 Ω (Note 1)	0.5 A



(Internal Schematic Diagram)



ORDERING INFORMATION

Device	Package	Shipping			
SMJB5603T4G	D2–PAK 2L (TO–263)	800 / Tape & Reel			

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

MARKING DIAGRAM

THERMAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise stated) (Note 2)

Parameter	Symbol	Мах	Unit
Thermal Resistance, Junction-to-Case	R _{θJC}	1.13	°C/W
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	76.42	

2. Device mounted on FR-4 PCB, board size = 76.2 mm x 114.3 mm, land pattern 12.70 mm x 9.45 mm, trace size = 10 mil.

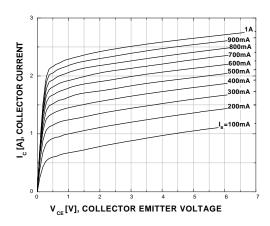
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise stated) (Note 3)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Collector-Base Breakdown Voltage	BV _{CBO}	I _C = 0.5 mA, I _E = 0	1500	1689		V
Collector-Emitter Breakdown Voltage	BV _{CEO}	$I_{\rm C} = 5 \text{ mA}, I_{\rm B} = 0$	800	870		V
Emitter-Base Breakdown Voltage	BV _{EBO}	I _E = 0.5 mA, I _C = 0	12.0	14.8		V
Collector Cut-off Current	I _{CES}	V _{CE} = 1500 V, V _{BE} = 0		0.01	100	μA
Collector Cut-off Current	I _{CEO}	V _{CE} = 800 V, I _B = 0		0.01	100	μΑ
Emitter Cut-off Current	I _{EBO}	V _{EB} = 12 V, I _C = 0		0.05	500	μΑ
DC Current Gain	h _{FE}	$V_{CE} = 3 \text{ V}, I_{C} = 0.4 \text{ A}$	20	29	35	
		V _{CE} = 10 V, I _C = 5 mA	20	43		
Collector-Emitter Saturation Voltage	V _{CE(sat)}	$I_{C} = 0.25 \text{ A}, I_{B} = 0.05 \text{ A}$		0.16		V
		I _C = 0.5 A, I _B = 0.167 A		0.12		
		I _C = 1 A, I _B = 0.33 A		0.25		
Base–Emitter Saturation Voltage	V _{BE(sat)}	I _C = 500 mA, I _B = 50 mA		0.74	1.20	V
		I _C = 2 A, I _B = 0.4 A		0.85	1.20	
Input Capacitance	C _{IB}	V _{EB} = 10 V, I _C = 0, f = 1 MHz 745		1000	pF	
Output Capacitance	C _{OB}	V _{CB} = 200 V, I _E = 0, f = 1 MHz 15			pF	
Current Gain Bandwidth Product	f _T	I _C = 0.1 A, V _{CE} = 10 V 5			MHz	
Diode Forward Voltage	V _F	I _F = 0.4 A	T	0.76	1.20	V
		I _F = 1 A		0.83	1.50	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse test: pulse width = 20 μ s, duty cycle \leq 10%.

TYPICAL CHARACTERISTICS





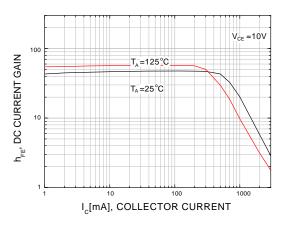


Figure 2. DC Current Gain

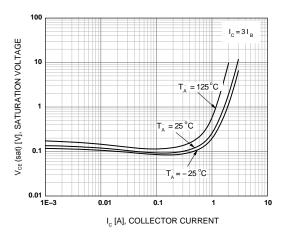


Figure 3. Collector–Emitter Saturation Voltage h_{FE} = 3

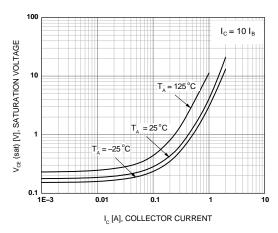


Figure 5. Collector–Emitter Saturation Voltage $h_{FE} = 10$

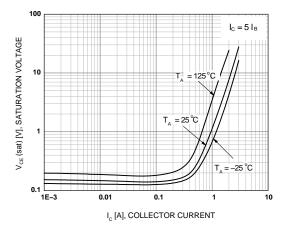


Figure 4. Collector–Emitter Saturation Voltage $h_{FE} = 5$

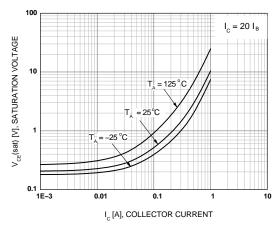


Figure 6. Collector–Emitter Saturation Voltage $h_{FE} = 20$

TYPICAL CHARACTERISTICS

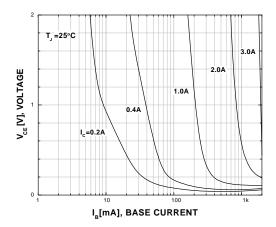


Figure 7. Typical Collector Saturation Voltage

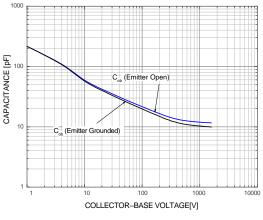


Figure 8. Capacitance

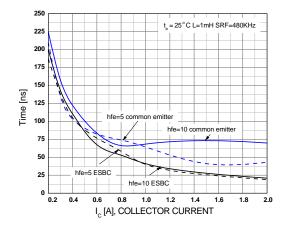


Figure 9. Inductive Load Collector Current Fall-Time (t_f)

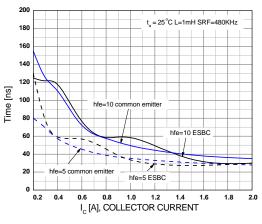


Figure 11. Inductive Load Collector Voltage Fall-Time (t_f)

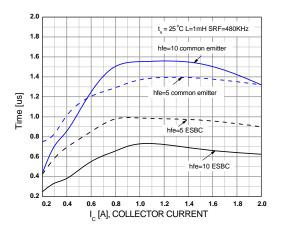


Figure 10. Inductive Load Collector Current Storage–Time (t_{stg})

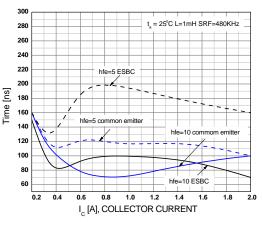


Figure 12. Inductive Load Collector Voltage Rise-Time (t_r)

TYPICAL CHARACTERISTICS

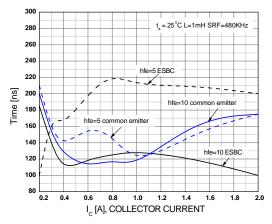


Figure 13. Inductive Load Collector Current / Voltage Crossover (t_c)

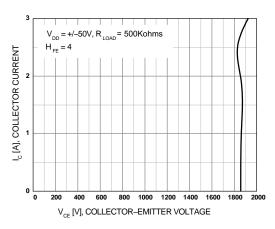


Figure 15. ESBC RBSOA

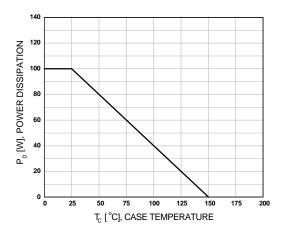


Figure 17. Power Derating

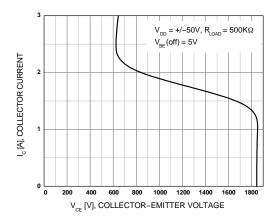


Figure 14. BJT Reverse Bias Safe Operating Area

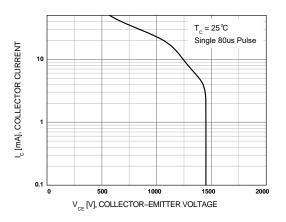


Figure 16. Crossover Forward Bias Safe Operating Area (FBSOA)

Test Circuits

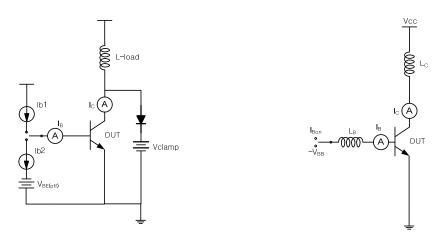
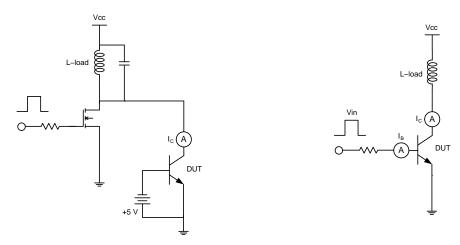


Figure 18. Test Circuit for Inductive Load and Reverse Bias Safe Operating





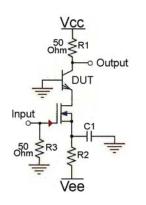


Figure 20. f_T Measurement

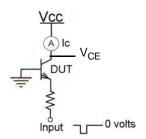


Figure 21. FBSOA

Test Circuits (Continued)

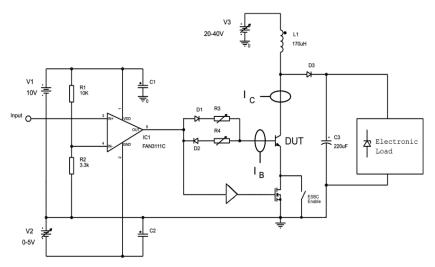


Figure 22. Simplified Saturated Switch Driver Circuit

Functional Test Waveforms

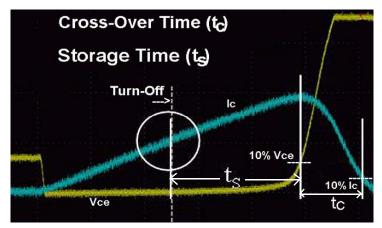


Figure 23. Crossover Time Measurement

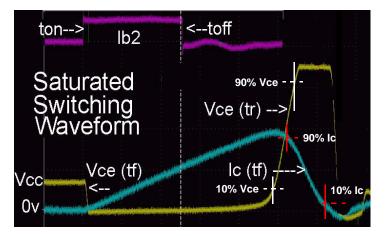


Figure 24. Saturated Switching Waveform

Functional Test Waveforms (Continued)

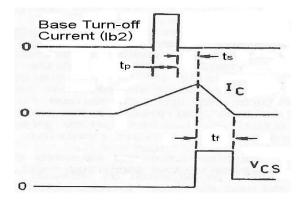


Figure 25. Storage Time – Common Emitter Base Turn-off (Ib2) to I_C Fall-Time

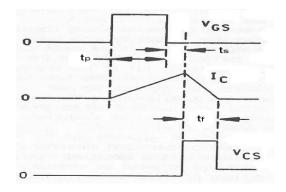
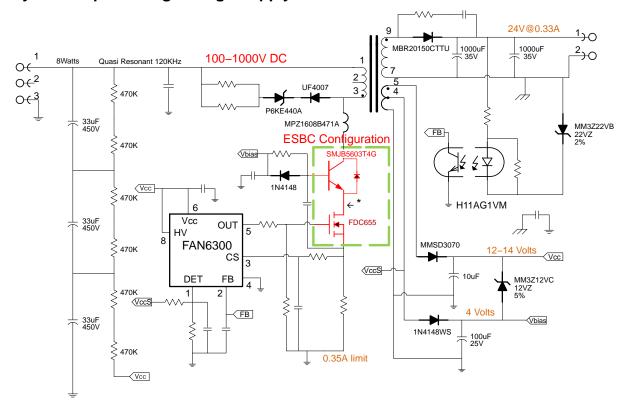


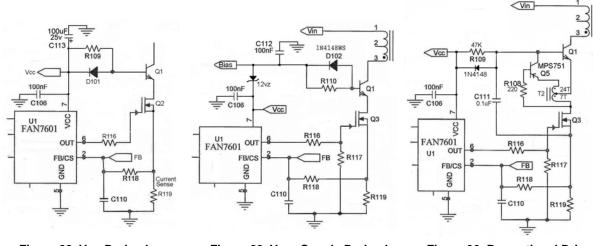
Figure 26. Storage Time – ESBC FET Gate (off) to I_{C} Fall–Time



Very Wide Input Voltage Range Supply

* Make short as possible

Figure 27. 8 W; Secondary-Side Regulation: 3 Capacitor Input; Quasi Resonant



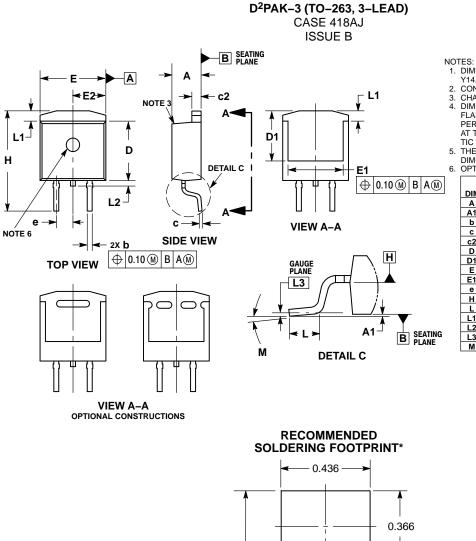
Driving ESBC Switches

Figure 28. V_{CC} Derived

Figure 29. V_{bias} Supply Derived



PACKAGE DIMENSIONS

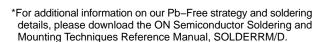


0.653

2X 0.063

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES. 3. CHAMFER OPTIONAL 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLAS-TIC BODY AT DATUM H. 5. THERMAI PAD CONTOUR IS OPTIONAL WITHIN
- 5. THERMAL PAD CONTOUR IS OPTIONAL WITHIN DIMENSIONS E, L1, D1 AND E1. 6. OPTIONAL MOLD FEATURE

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.160	0.190	4.06	4.83
A1	0.000	0.010	0.00	0.25
b	0.020	0.039	0.51	0.99
С	0.012	0.029	0.30	0.74
c2	0.045	0.065	1.14	1.65
D	0.330	0.380	8.38	9.65
D1	0.260		6.60	
Е	0.380	0.420	9.65	10.67
E1	0.245		6.22	
е	0.100	BSC	BSC 2.54 BSC	
Н	0.575	0.625	14.60	15.88
L	0.070	0.110	1.78	2.79
L1		0.066		1.68
L2		0.070		1.78
L3	0.010 BSC		0.25	BSC
М	0°	8°	0°	8°



۲ ^{2X} 0.169 .

0.100 PITCH DIMENSIONS: INCHES

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